RELIABILITY REPORT

FOR

MAX1558HETB+

PLASTIC ENCAPSULATED DEVICES

May 18, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX1558HETB+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX1558/MAX1558H are dual, current-limited switches with autoreset for USB applications. Autoreset latches the switch off if it is shorted for more than 20ms, saving system power. The shorted output is then tested to determine when the short is removed to automatically restart the channel. Each channel delivers up to 1.2A and meets all IEC specifications for USB ports. Low quiescent supply current (45µA) and standby current (3µA) conserve battery power in portable applications. The MAX1558/MAX1558H safety features ensure that the USB port is protected. Built-in thermal-overload protection limits power dissipation and junction temperature. Accurate, programmable current-limiting circuitry protects the input supply against both overload and short-circuit conditions. 20ms fault blanking enables the circuit to ignore transient faults, such as those caused when hot swapping a capacitive load, preventing false alarms to the host system. The MAX1558/MAX1558H also feature reverse-current protection circuitry to block current flow from the output to the input when the switches are off. The MAX1558/MAX1558H are available in space-saving 3mm x 3mm, 10-pin TDFN packages. The MAX1558 is enabled with an active-low signal, and the MAX1558H is enabled with an active-high signal.

II. Manufacturing Information

A. Description/Function:	Dual, 3mm x 3mm, 1.2A/Programmable-Current USB Switches with Autoreset
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Texas
E. Assembly Location:	Philippines, China, Thailand, Malaysia
F. Date of Initial Production:	July 24, 2004

III. Packaging Information

A. Package Type:	10-pin TDFN 3x3
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0701
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	54°C/W
K. Single Layer Theta Jc:	8.5°C/W
L. Multi Layer Theta Ja:	41°C/W
M. Multi Layer Theta Jc:	8.5°C/W

IV. Die Information

A. Dimensions:	94 X 63 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide
C. Interconnect:	Aluminum/0.5% Copper
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 48 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.4 \times 10^{-9}$

$\lambda = 22.4$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the B8 Process results in a FIT Rate of 1.86 @ 25C and 22.5 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The PN21-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2000 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX1558HETB+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data